

Features

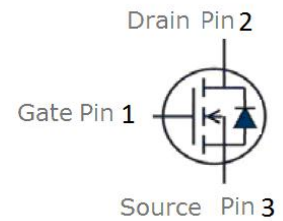
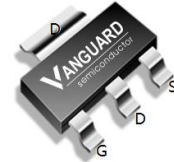
- N-Channel, 5V Logic Level Control
- Enhancement mode
- Low on-resistance @ $V_{GS}=4.5\text{ V}$
- Fast Switching
- Pb-free lead plating; RoHS compliant

V_{DS}	150	V
$R_{DS(on),typ@VGS=10V}$	230	m Ω
$R_{DS(on),typ@VGS=4.5V}$	235	m Ω
I_D	3	A



Part ID	Package Type	Marking	Tape and reel information
VSZ280N15MS	SOT223	280N15M	2500pcs/reel

SOT223



Maximum ratings, at $T_j=25\text{ }^\circ\text{C}$, unless otherwise specified

Symbol	Parameter	Rating	Unit	
$V_{(BR)DSS}$	Drain-Source breakdown voltage	150	V	
V_{GS}	Gate-Source voltage	± 20	V	
I_D	Continuous drain current@ $V_{GS}=10V$	$T_A=25^\circ\text{C}$	3	A
		$T_A=100^\circ\text{C}$	1.9	A
I_{DM}	Pulse drain current tested ①	$T_A=25^\circ\text{C}$	12	A
P_D	Maximum power dissipation	$T_A=25^\circ\text{C}$	4.1	W
I_S	Diode Continuous Forward Current	$T_A=25^\circ\text{C}$	3	A
$T_{STG} T_J$	Storage and operating temperature range①	-55 to 150	$^\circ\text{C}$	
Thermal characteristics				
$R_{\theta JA}$	Thermal Resistance Junction-Ambient	30	$^\circ\text{C/W}$	
$R_{\theta JC}$	Thermal Resistance-Junction to Case	15	$^\circ\text{C/W}$	
Drain-Source Avalanche Ratings				
EAS	Avalanche Energy, Single Pulsed ③	9	mJ	

Typical Electrical Characteristics

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
Static Electrical Characteristics @ T_J = 25°C (unless otherwise stated)						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	150	--	--	V
I _{DSS}	Zero Gate Voltage Drain Current(Tc=25°C)	V _{DS} =150V, V _{GS} =0V	--	--	1	μA
	Zero Gate Voltage Drain Current(Tc=125°C)	V _{DS} =150V, V _{GS} =0V	--	--	100	μA
I _{GSS}	Gate-Body Leakage Current	V _{GS} =±20V, V _{DS} =0V	--	--	±100	nA
V _{GS(TH)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	1.0	2.0	3.0	V
R _{DS(ON)}	Drain-Source On-State Resistance ^②	V _{GS} =10V, I _D =3A	--	230	280	mΩ
R _{DS(ON)}	Drain-Source On-State Resistance ^②	V _{GS} =4.5V, I _D =2A	--	235	300	mΩ
Dynamic Electrical Characteristics @ T_J = 25°C (unless otherwise stated)						
C _{iss}	Input Capacitance	V _{DS} =30V, V _{GS} =0V, f=1MHz	--	560	--	pF
C _{oss}	Output Capacitance		--	30	--	pF
C _{rss}	Reverse Transfer Capacitance		--	25	--	pF
Q _g	Total Gate Charge	V _{DS} =75V, I _D =3A, V _{GS} =10V	--	19	--	nC
Q _{gs}	Gate-Source Charge		--	5	--	nC
Q _{gd}	Gate-Drain Charge		--	5.2	--	nC
Switching Characteristics						
t _{d(on)}	Turn-on Delay Time	V _{DD} =75V, I _D =1A, R _G =6.8Ω, V _{GS} =4.5V	--	12	--	nS
t _r	Turn-on Rise Time		--	6	--	nS
t _{d(off)}	Turn-Off Delay Time		--	15.5	--	nS
t _f	Turn-Off Fall Time		--	4.5	--	nS
Source- Drain Diode Characteristics @ T_J = 25°C (unless otherwise stated)						
V _{SD}	Forward on voltage	I _{SD} =3A, V _{GS} =0V	--	0.81	1.2	V
t _{rr}	Reverse Recovery Time	T _J =25°C, I _{sd} =2A, V _{GS} =0V di/dt=100A/μs	--	21	--	nS
Q _{rr}	Reverse Recovery Charge		--	28	--	nC

NOTE:

- ① Repetitive rating; pulse width limited by max. junction temperature
- ② Pulse width ≤ 300μs; duty cycles ≤ 2%.
- ③ Limited by T_{Jmax}, starting T_J = 25°C, L = 0.5mH, R_G = 25Ω, I_{AS} = 6A V_{GS} = 10V. Part not recommended for use above this value

Typical Characteristics

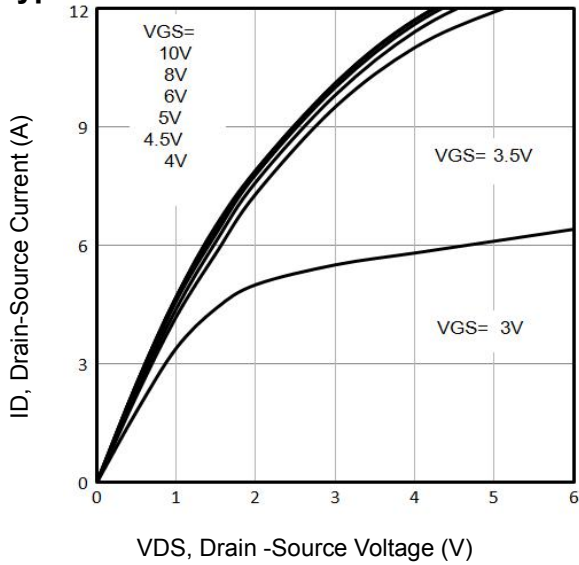


Fig1. Typical Output Characteristics

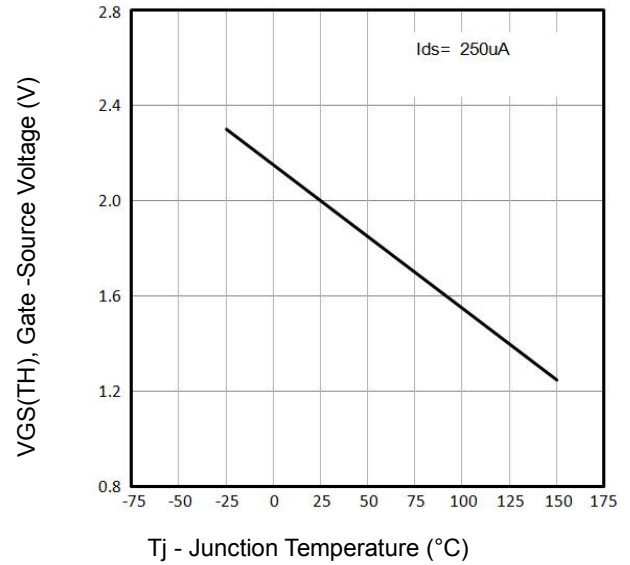


Fig2. $V_{GS(TH)}$ Gate-Source Voltage Vs. T_j

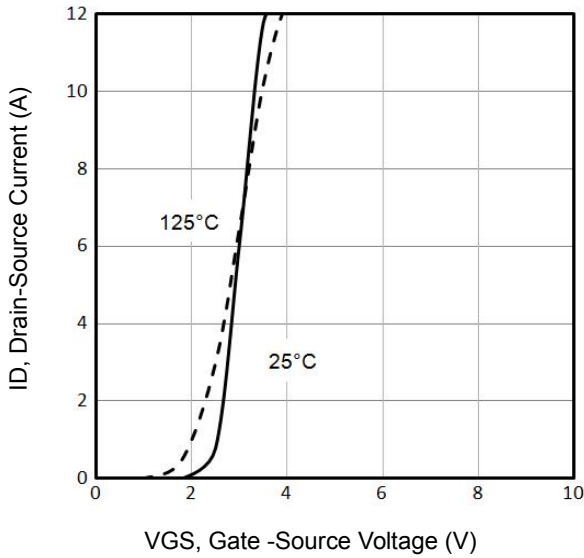


Fig3. Typical Transfer Characteristics

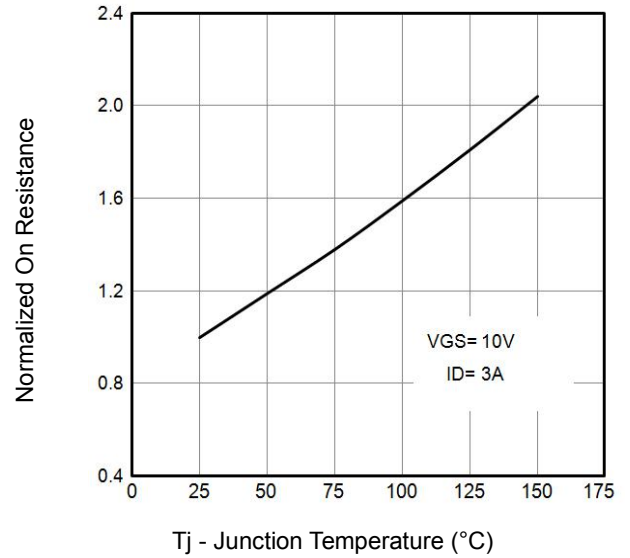


Fig4. Normalized On-Resistance Vs. T_j

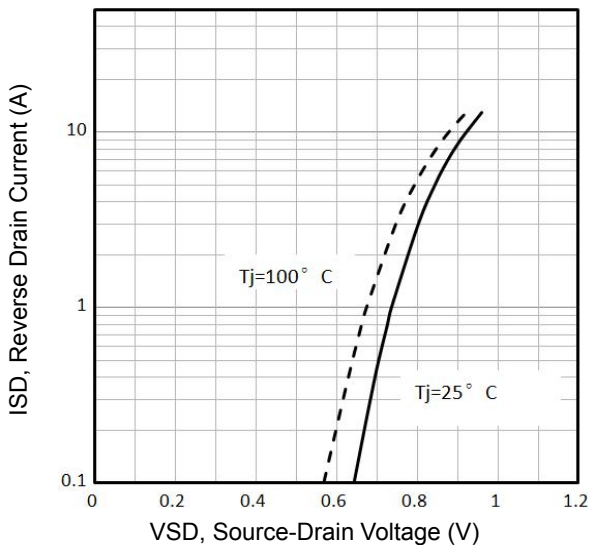


Fig5. Typical Source-Drain Diode Forward Voltage

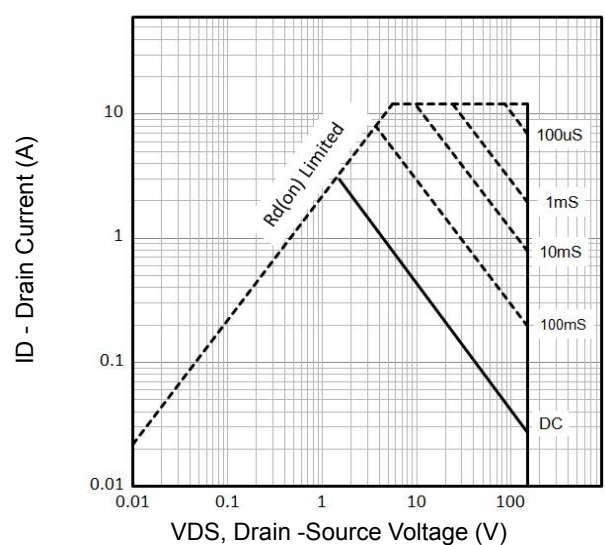


Fig6. Maximum Safe Operating Area

Typical Characteristics

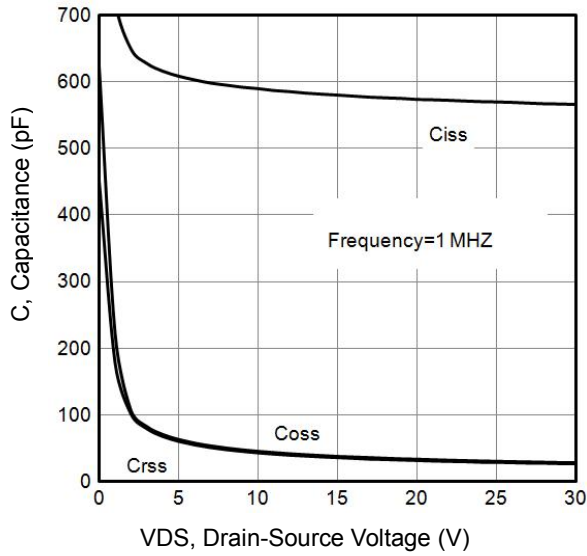


Fig7. Typical Capacitance Vs. Drain-Source Voltage

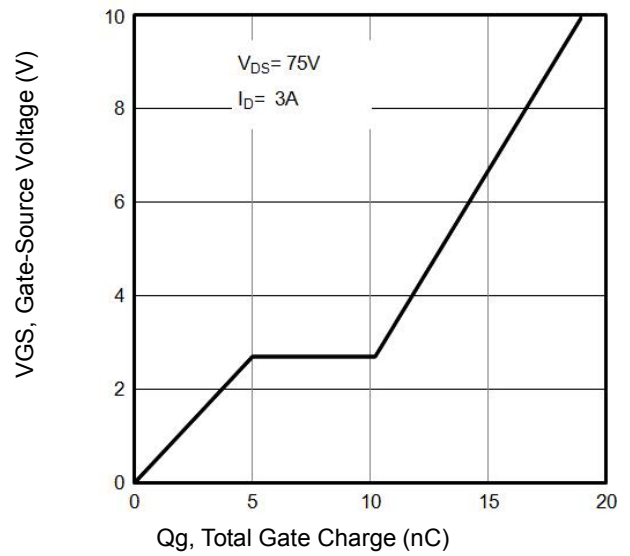


Fig8. Typical Gate Charge Vs. Gate-Source Voltage

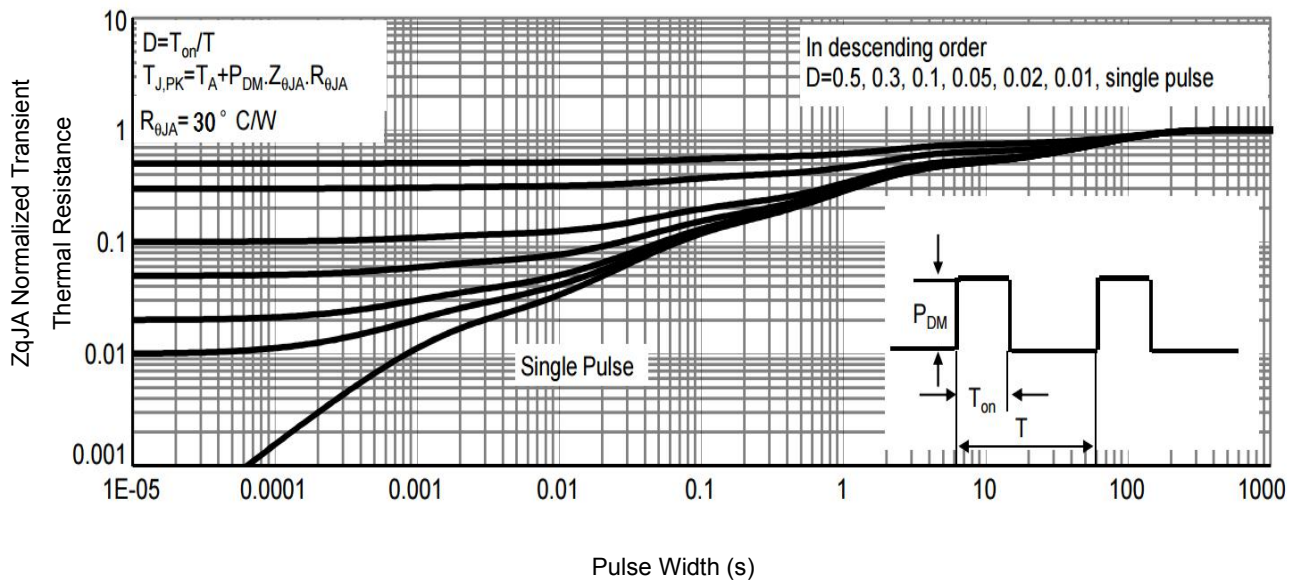


Fig9. Normalized Maximum Transient Thermal Impedance

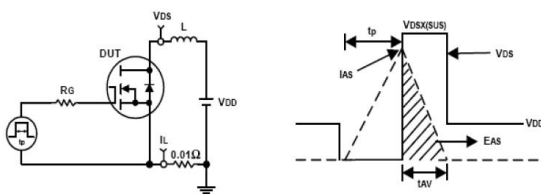


Fig10. Unclamped Inductive Test Circuit and waveforms

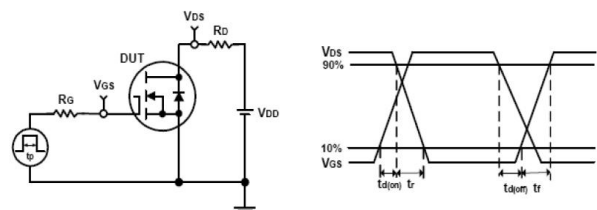
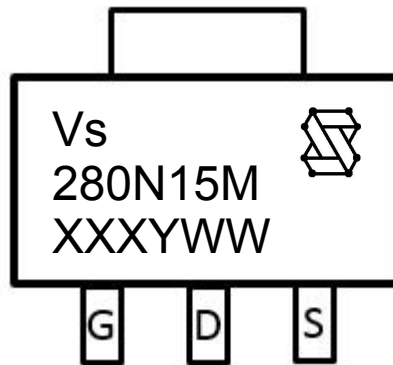


Fig11. Switching Time Test Circuit and waveforms

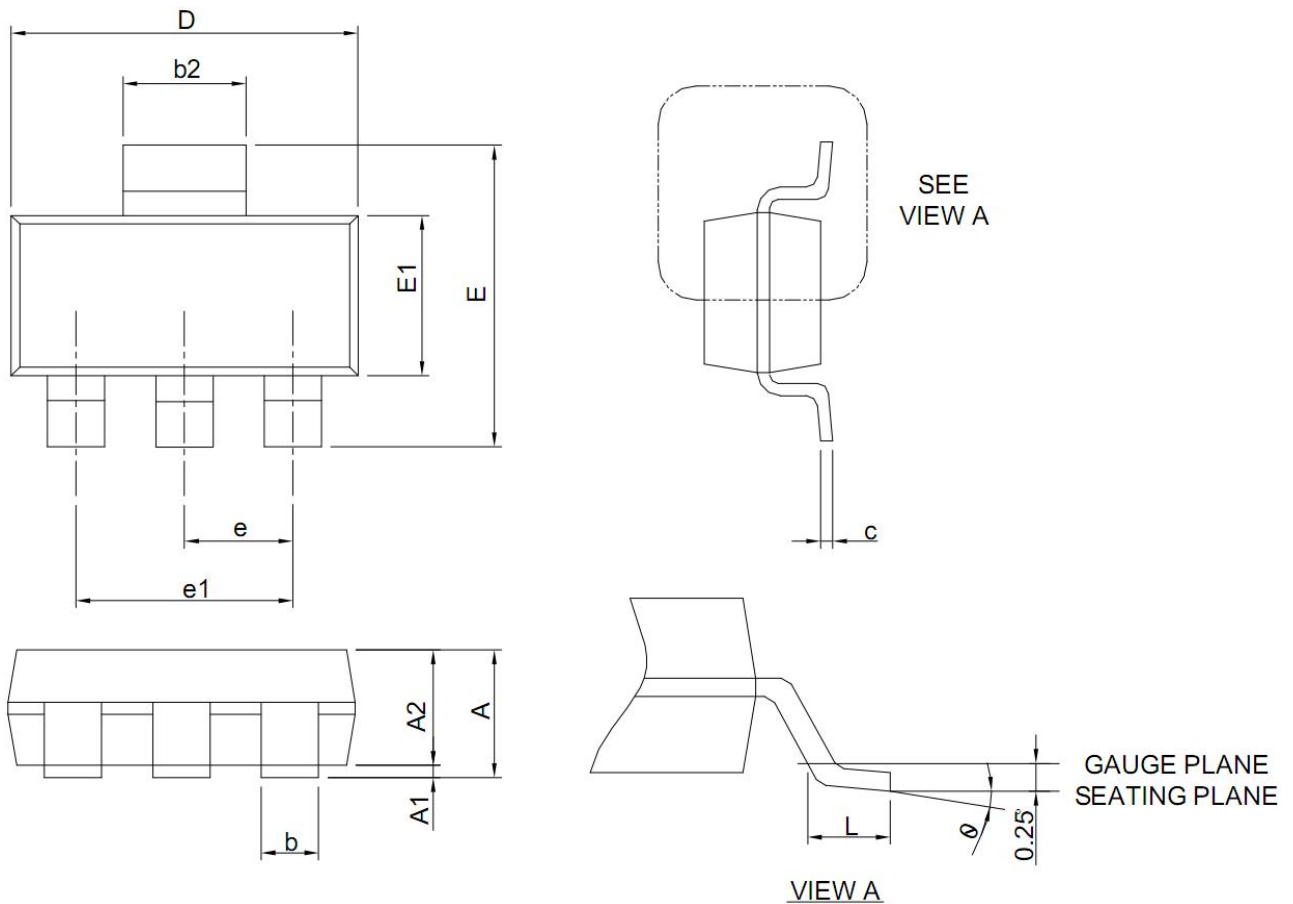


Marking Information



- 1st line: Vanguard Code (Vs), Vanguard Logo
2nd line: Part Number (280N15M)
3rd line: Date code (XXXYWW)
XXX: Wafer Lot Number Code , code changed with Lot Number
Y: Year Code, (e.g. E=2017, F=2018, G=2019, H=2020, etc)
WW: Week Code (01 to 53)

SOT223 Package Outline Data



Symbol	Dimensions (unit: mm)		
	Min	Typ	Max
A	1.50	1.65	1.80
A1	0.02	0.06	0.10
A2	1.50	1.60	1.70
b	0.66	0.72	0.80
b2	2.90	3.00	3.10
c	0.23	0.30	0.35
D	6.30	6.50	6.70
E	6.70	7.00	7.30
E1	3.30	3.50	3.70
e	2.30 REF		
e1	4.60 REF		
L	0.75	--	1.15
θ	0 °	--	10 °

Notes:

1. Refer to JEDEC TO-261 variation AA
2. Dimensions "D" and "E1" do NOT include mold flash, tie bar burrs, gate burrs and interlead flash.

Customer Service

Sales and Service:

sales@vgsemi.com

Vanguard Semiconductor CO., LTD

TEL: (86-755) -26902410

FAX: (86-755) -26907027

WEB: www.vgsemi.com